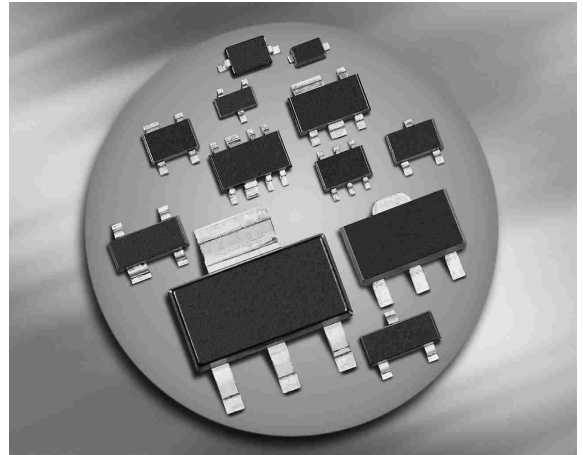
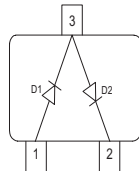
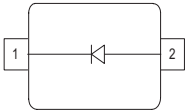


Silicon PIN Diode

- For low loss RF switches and attenuators
- Very low capacitance at zero volt reverse bias at frequencies above 1 GHz (typ. 0.25 pF)
- Low forward resistance (typ. 1.5 Ω @ 5mA)
- Low harmonics
- Pb-free (RoHS compliant) package


BAR67-02V
BAR67-04


| Type | Package | Configuration | L_S (nH) | Marking |
|-----------|---------|---------------|------------|---------|
| BAR67-02V | SC79 | single | 0.6 | T |
| BAR67-04 | SOT23 | series | 1.8 | PMs |

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

| Parameter | Symbol | Value | Unit |
|--|-----------|-------------|------------------|
| Diode reverse voltage | V_R | 150 | V |
| Forward current | I_F | 200 | mA |
| Total power dissipation | P_{tot} | | mW |
| $T_S \leq 118^\circ\text{C}$, BAR67-02V | | 250 | |
| $T_S \leq 25^\circ\text{C}$, BAR67-04 | | 250 | |
| Junction temperature | T_j | 150 | $^\circ\text{C}$ |
| Operating temperature range | T_{op} | -55 ... 125 | |
| Storage temperature | T_{stg} | -55 ... 150 | |

Thermal Resistance

| Parameter | Symbol | Value | Unit |
|--|------------|------------|------|
| Junction - soldering point ¹⁾ | R_{thJS} | | K/W |
| BAR67-02V | | ≤ 115 | |
| BAR67-04 | | ≤ 290 | |

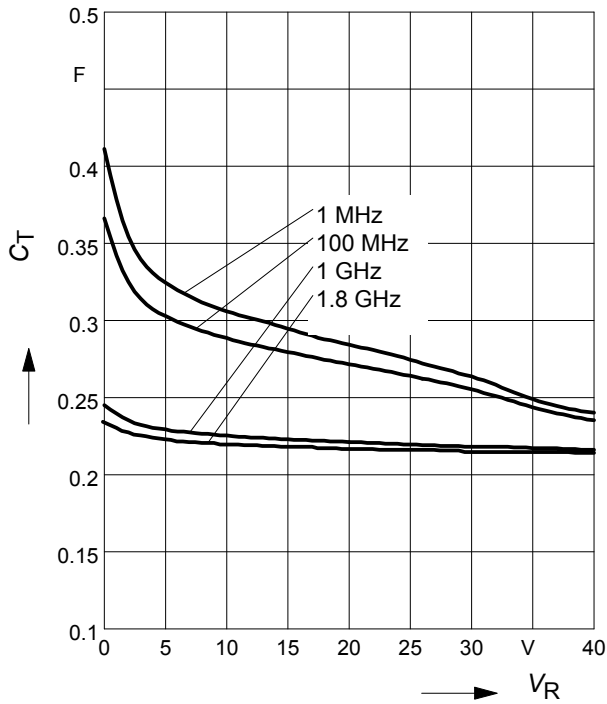
¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

| Parameter | Symbol | Values | | | Unit |
|---|-------------|--------|------|------|---------------|
| | | min. | typ. | max. | |
| DC Characteristics | | | | | |
| Breakdown voltage $I_{(BR)} = 5 \mu\text{A}$ | $V_{(BR)}$ | 150 | - | - | V |
| Reverse current $V_R = 100 \text{ V}$ | I_R | - | - | 20 | nA |
| Forward voltage $I_F = 50 \text{ mA}$ | V_F | - | 0.95 | 1.2 | V |
| AC Characteristics | | | | | |
| Diode capacitance $V_R = 5 \text{ V}, f = 1 \text{ MHz}$ $V_R = 0 \text{ V}, f = 100 \text{ MHz}$ $V_R = 0 \text{ V}, f = 1 \text{ GHz}$ $V_R = 0 \text{ V}, f = 1.8 \text{ GHz}$ | C_T | - | 0.35 | 0.55 | pF |
| Reverse parallel resistance $V_R = 0 \text{ V}, f = 100 \text{ MHz}$ $V_R = 0 \text{ V}, f = 1 \text{ GHz}$ $V_R = 0 \text{ V}, f = 1.8 \text{ GHz}$ | R_P | - | 25 | - | k Ω |
| Forward resistance $I_F = 5 \text{ mA}, f = 100 \text{ MHz}$ $I_F = 10 \text{ mA}, f = 100 \text{ MHz}$ | r_f | - | 1.5 | 1.8 | Ω |
| Charge carrier life time $I_F = 10 \text{ mA}, I_R = 6 \text{ mA}$, measured at $I_R = 3 \text{ mA}$, $R_L = 100 \Omega$ | τ_{rr} | - | 700 | - | ns |
| I-region width | W_I | - | 13 | - | μm |

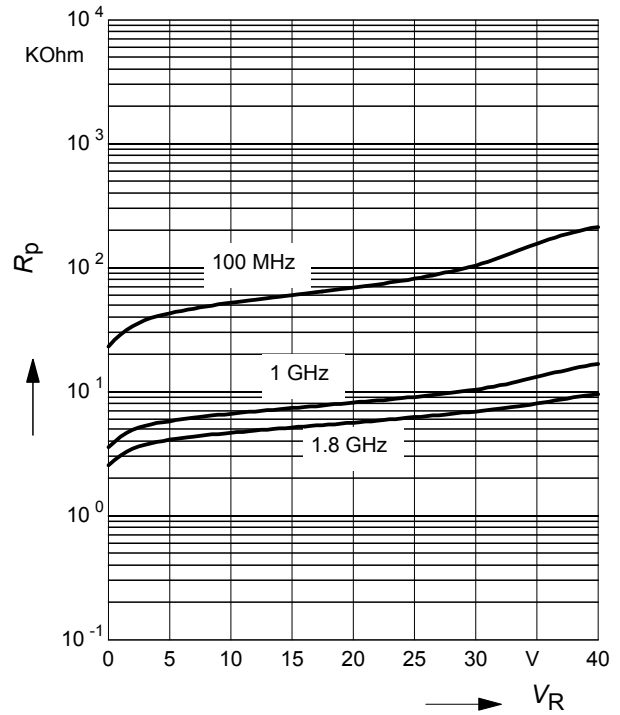
Diode capacitance $C_T = f(V_R)$

$f =$ Parameter



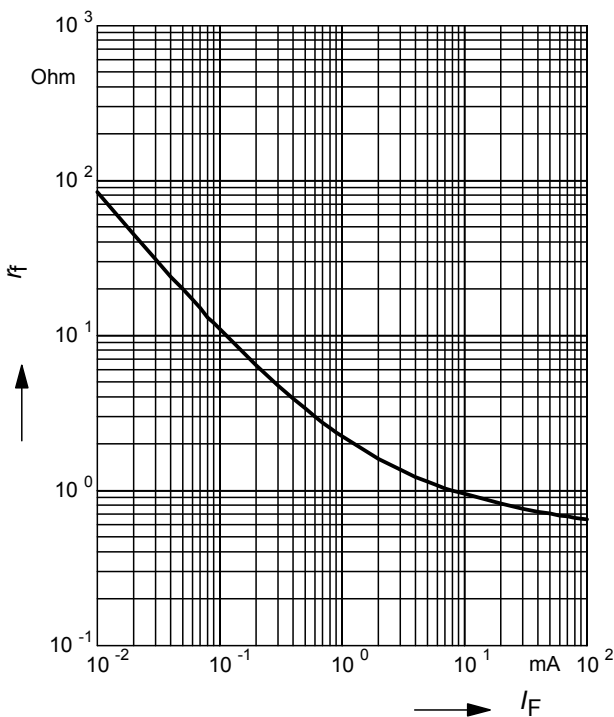
Reverse parallel resistance $R_P = f(V_R)$

$f =$ Parameter



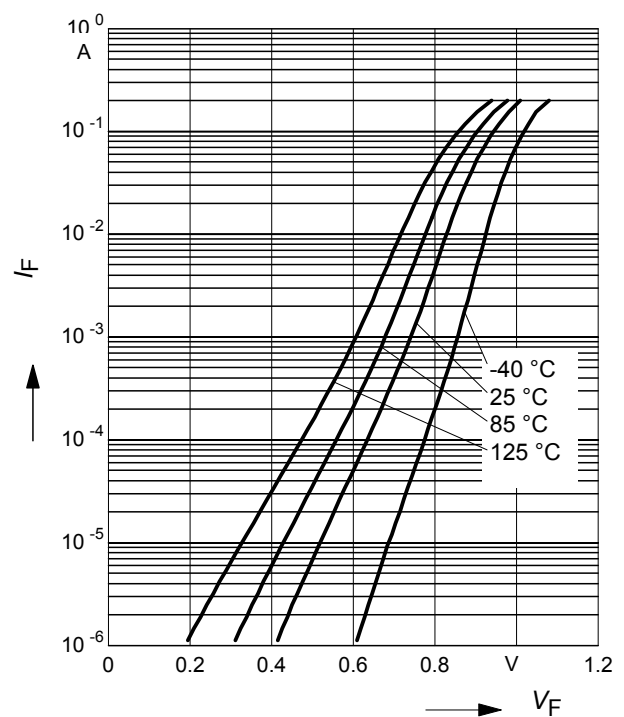
Forward resistance $r_f = f(I_F)$

$f = 100\text{MHz}$



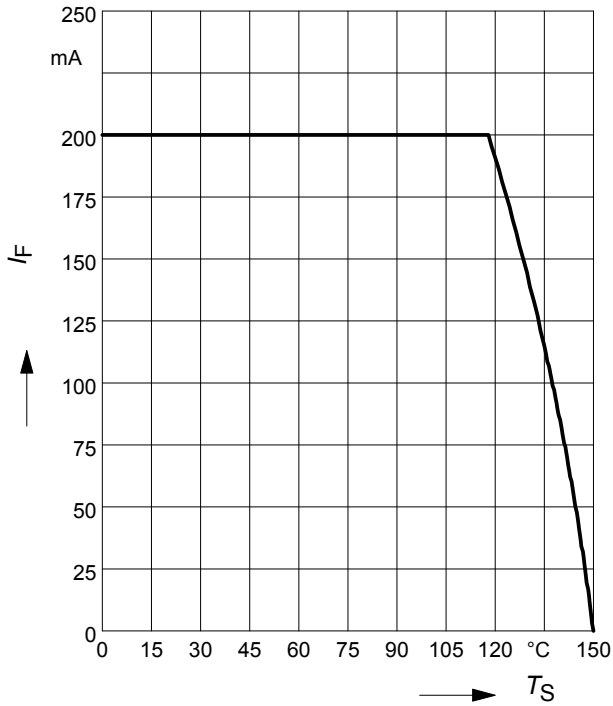
Forward current $I_F = f(V_F)$

$T_A =$ Parameter



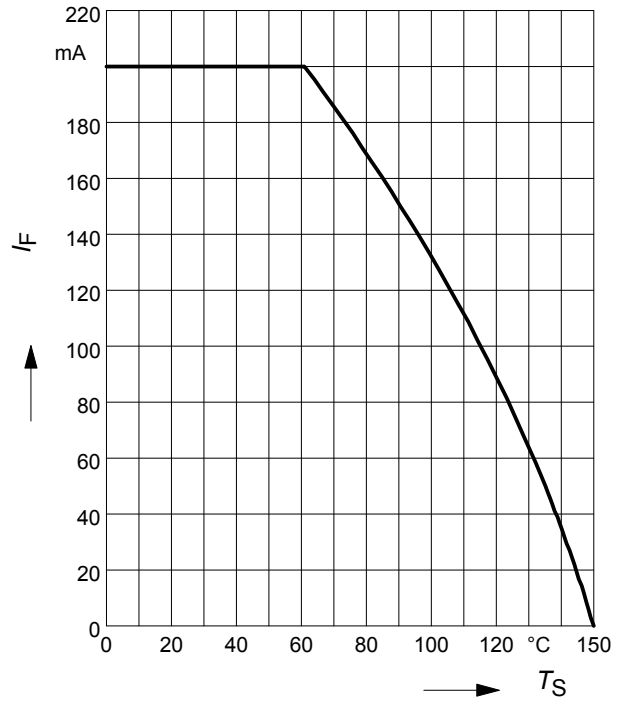
Forward current $I_F = f(T_S)$

BAR67-02V



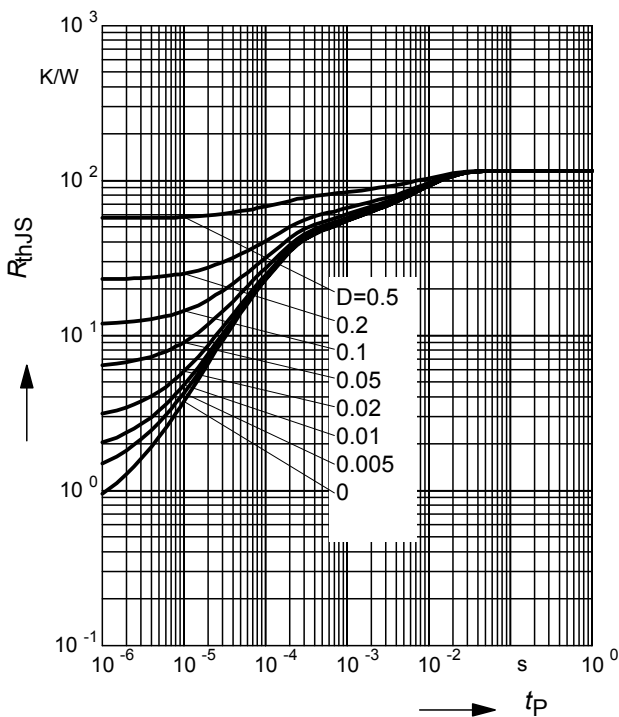
Forward current $I_F = f(T_S)$

BAR67-04



Permissible Puls Load $R_{thJS} = f(t_p)$

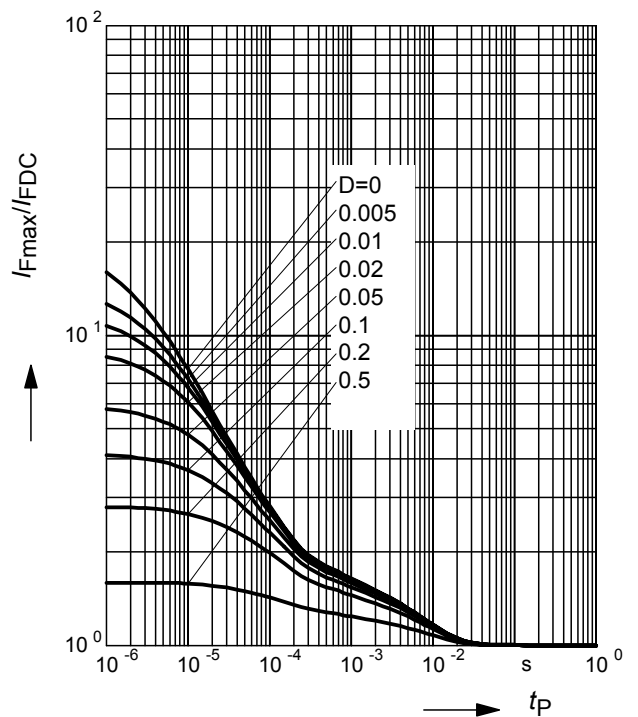
BAR67-02V



Permissible Pulse Load

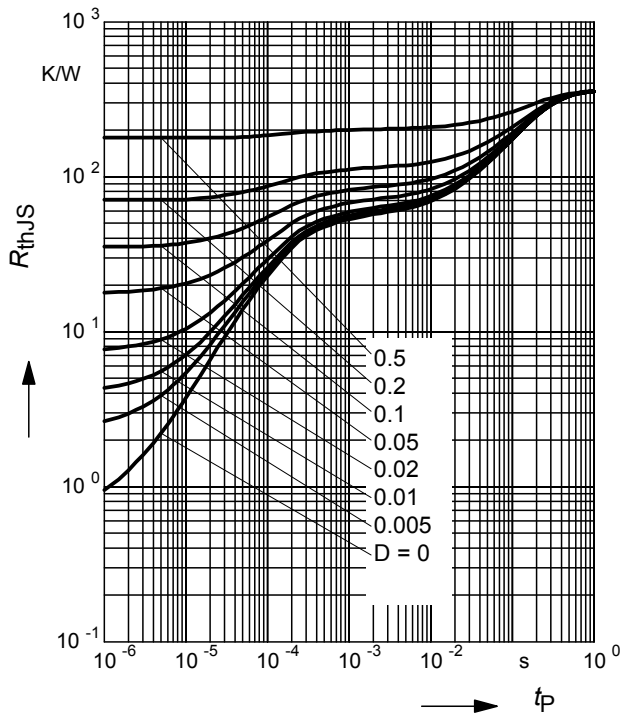
$I_{Fmax} / I_{FDC} = f(t_p)$

BAR67-02V

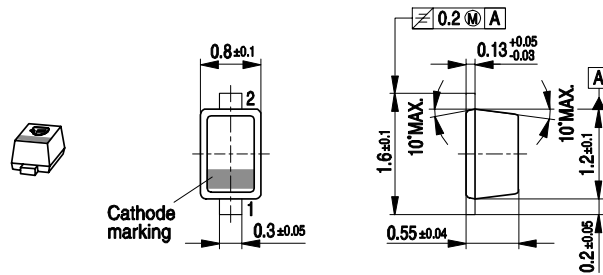


Permissible Puls Load $R_{thJS} = f(t_p)$

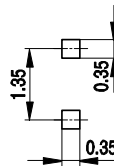
BAR67-04



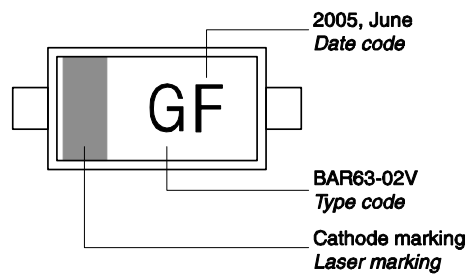
Package Outline



Foot Print

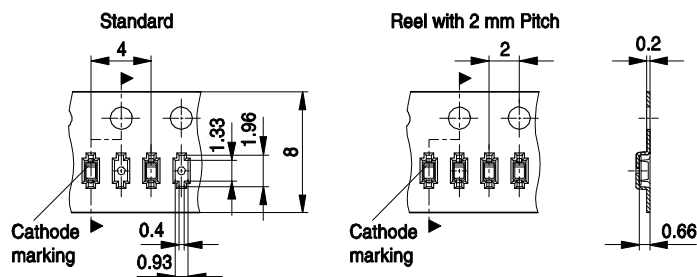


Marking Layout (Example)



Standard Packing

- Reel \varnothing 180 mm = 3.000 Pieces/Reel
- Reel \varnothing 180 mm = 8.000 Pieces/Reel (2 mm Pitch)
- Reel \varnothing 330 mm = 10.000 Pieces/Reel

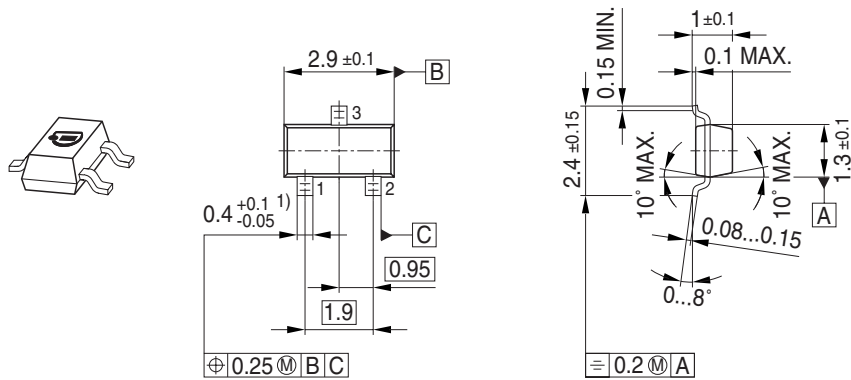


Date Code marking for discrete packages with one digit (SCD80, SC79, SC75¹⁾) CES-Code

| Month | 2003 | 2004 | 2005 | 2006 | 2007 | 2008 | 2009 | 2010 | 2011 | 2012 | 2013 | 2014 |
|-------|------|------|------|------|------|------|------|------|------|------|------|------|
| 01 | a | p | A | P | a | p | A | P | a | p | A | P |
| 02 | b | q | B | Q | b | q | B | Q | b | q | B | Q |
| 03 | c | r | C | R | c | r | C | R | c | r | C | R |
| 04 | d | s | D | S | d | s | D | S | d | s | D | S |
| 05 | e | t | E | T | e | t | E | T | e | t | E | T |
| 06 | f | u | F | U | f | u | F | U | f | u | F | U |
| 07 | g | v | G | V | g | v | G | V | g | v | G | V |
| 08 | h | x | H | X | h | x | H | X | h | x | H | X |
| 09 | j | y | J | Y | j | y | J | Y | j | y | J | Y |
| 10 | k | z | K | Z | k | z | K | Z | k | z | K | Z |
| 11 | l | 2 | L | 4 | l | 2 | L | 4 | l | 2 | L | 4 |
| 12 | n | 3 | N | 5 | n | 3 | N | 5 | n | 3 | N | 5 |

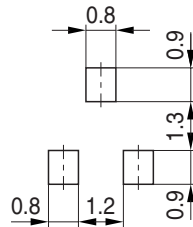
1) New Marking Layout for SC75, implemented at October 2005.

Package Outline

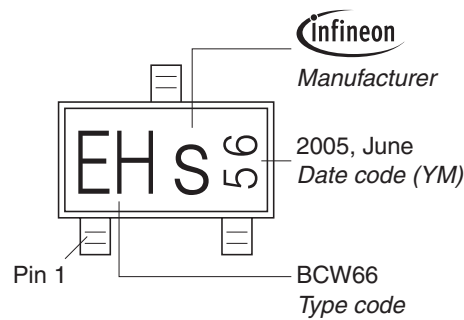


1) Lead width can be 0.6 max. in dambar area

Foot Print

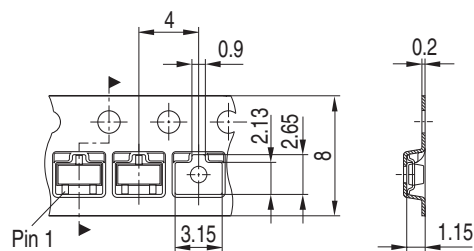


Marking Layout (Example)



Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



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